

(19) World Intellectual Property  
Organization  
International Bureau



(43) International Publication Date  
10 September 2004 (10.09.2004)

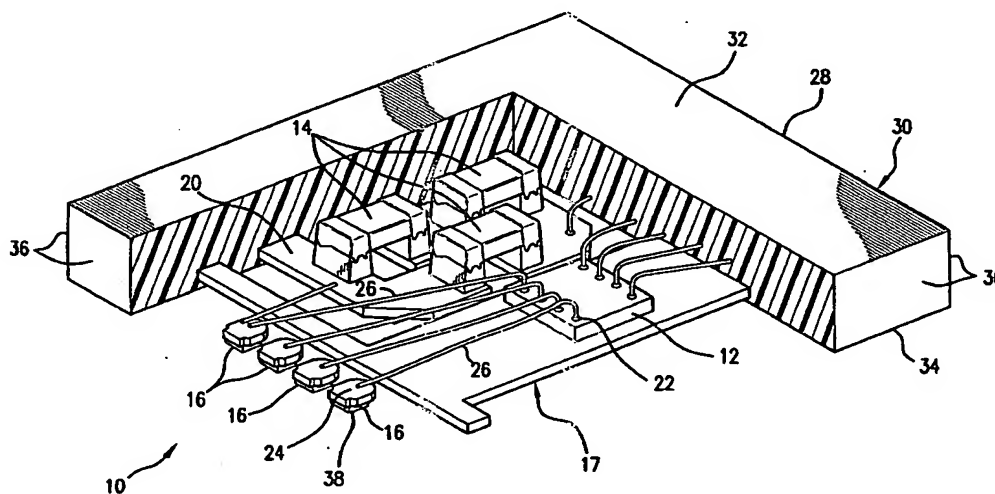
PCT

(10) International Publication Number  
**WO 2004/077508 A2**

- (51) International Patent Classification<sup>7</sup>: **H01L** (74) Agent: **OLSON, Timothy, J.**; Wiggin & Dana LLP, One Century Tower, New Haven, CT 06508-1832 (US).
- (21) International Application Number: PCT/US2004/004676 (81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.
- (22) International Filing Date: 17 February 2004 (17.02.2004)
- (25) Filing Language: English
- (26) Publication Language: English
- (30) Priority Data:  
60/449,049 21 February 2003 (21.02.2003) US
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- (84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).
- Published:  
— without international search report and to be republished upon receipt of that report

[Continued on next page]

(54) Title: **LEAD FRAME WITH INCLUDED PASSIVE DEVICES**



(57) Abstract: An semiconductor device package (10) includes a semiconductor device (die) (12) and passive devices (14) electrically connected to a common lead frame (17). The lead frame (17) is formed from a stamped and/or etched metallic structure and includes a plurality of conductive leads (16) and a plurality of interposers (20). The passive devices (14) are electrically connected to the interposers (20), and I/O pads (22) on the die (12) are electrically connected to the leads (16). The die (12), passive devices (14), and lead frame (17) are encapsulated in a molding compound (28), which forms a package body (30). Bottom surfaces (38) of the leads (16) are exposed at a bottom face (34) of the package (10).

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*For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.*